PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
IKUROH ICHITSUBO	05/08/2017
GUAN-WU WANG	05/03/2017
WEIPING WANG	05/02/2017

RECEIVING PARTY DATA

Name:	MICRO MOBIO CORPORATION	
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PROPERTY NUMBERS Total: 1

Property Type	Number
Patent Number:	7221225

CORRESPONDENCE DATA

Fax Number:

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

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NAME OF SUBMITTER:

CHRISTOPHER J. HORGAN

/Christopher J. Horgan/

DATE SIGNED:

05/13/2017

This document serves as an Oath/Declaration (37 CFR 1.63).

Total Attachments: 1

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PATENT REEL: 042369 FRAME: 0510

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ASSIGNMENT OF PATENT APPLICATION

WHEREAS, INVENTORs <u>Ikuroh Ichitsubo</u>, <u>Guan-Wu Wang</u>, <u>and Weiping Wang</u> hereinafter referred to as "Assignors," are the inventors of the invention described and set forth in the below-identified application for United States Letters Patent:

Title of Invention: DUAL BAND POWER AMPLIFIER MODULE FOR WIRELESS COMMUNICATION DEVICES;

Filing Date: July 2, 2005;

Docket No.: ____;

Application No.: 11/173,965; Patent No.: 7,221,225; and

WHEREAS, <u>Micro Mobio Corporation</u>, located at 2275 East Bayshore Road, Suite 150, Palo Alto, CA 94303, hereinafter referred to as "ASSIGNEE," is desirous of acquiring an interest in the invention and application and in any U.S. Letters Patent and Registrations which may be granted on the same.

For good and valuable consideration, receipt of which is hereby acknowledged by Assignors, Assignors have assigned, and by these presents do assign to Assignee all right, title and interest in and to the invention and application and to all foreign counterparts (including patent, utility model and industrial designs), and in and to any Letters Patent and Registrations which may hereafter be granted on the same in the United States and all countries throughout the world, and to claim the priority from the application as provided by the Paris Convention. The right, title and interest is to be held and enjoyed by Assignee and Assignee's successors and assigns as fully and exclusively as it would have been held and enjoyed by Assignors had this Assignment not been made, for the full term of any Letters Patent and Registrations which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignors further agree that they will, without charge to Assignee, but at Assignee's expense, (a) cooperate with Assignee in the prosecution of U.S. Patent applications and foreign counterparts on the invention and any improvements, (b) execute, verify, acknowledge and deliver all such further papers, including patent applications and instruments of transfer, and (c) perform such other acts as Assignee lawfully may request to obtain or maintain Letters Patent and Registrations for the invention and improvements in any and all countries, and to vest title thereto in Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignors have signed their names on the dates indicated.

Dated:

Dated:

Dated:

5/2/2017

Tkuroh Ichitsubo

Guan-Wu Wang

Weiping Wang

PATENT REEL: 042369 FRAME: 0511

RECORDED: 05/13/2017